

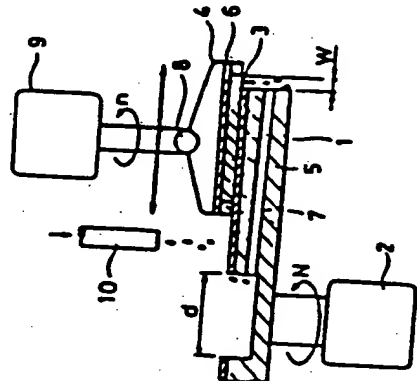
PATENTS ABSTRACTS OF JAPAN

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(54) METHOD AND APPARATUS FOR WAFER POLISHING
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(71) HITACHI LTD (72) HAJIME YUICHI
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PURPOSE: To enable accurately polish a wafer into plane form, by polishing the wafer held in a polishing chuck with a part thereof sticking out from a polishing surface plate or a polishing cloth.

CONSTITUTION: Each polishing chuck 4 holds one semiconductor wafer 5, which is polished with a part thereof sticking out from a polishing surface plate 1 or a polishing cloth 3. For example, the semiconductor wafer 5 to be polished is held by the polishing chuck 4 by vacuum absorption or any other means, rotating the polishing chuck 4 with a motor 9 forces the semiconductor wafer 5 to rotate together with the polishing chuck 4 at a rotating speed n and presses the wafer 5 on the polishing cloth 3 at a rotating speed n and presses this state rotates together with the polishing surface plate 1 forcibly while reciprocating in the direction of the diameter of the polishing speed n plate 1 and is polished by the friction between said wafer and the polishing cloth 3, with a part thereof sticking out from the polishing cloth 3 in the inside and outside of the polishing surface plate 1.



LEGENDE zu den Bibliographiedaten (54) Titel der Patentanmeldung
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